

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E.

PATENT DATE

SCANNED

9

APPLICATION NO.
09/99680

CONT/PRIOR
F

CLASS
428

SUBCLASS
4.2

ART UNIT 1712
~~1773~~

EXAMINER

APPLICANTS

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TIME

Resin compound for fabricating interlayer dielectric of printed wiring board, resin sheet and resin applied-copper foil for forming insulating layer using the resin compound, and copper-clad laminate using them

PTO-2040
12/99

ISSUING CLASSIFICATION

[illegible]

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	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
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